

Title (en)

COMPOSITION AND METHOD FOR REDUCING COPPER OXIDE TO METALLIC COPPER

Title (de)

ZUSAMMENSETZUNG UND METHODE ZUM REDUZIEREN VON KUPFEROXID ZU KUPFERMETALL

Title (fr)

COMPOSITION ET PROCEDE PERMETTANT DE REDUIRE L'OXYDE DE CUIVRE EN CUIVRE METALLIQUE

Publication

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Application

**EP 98908643 A 19980220**

Priority

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Abstract (en)

[origin: CA2254362A1] A composition for reducing a copper oxide layer to metallic copper so as to facilitate bonding a resin to the metallic copper is disclosed. The composition is an aqueous reducing solution containing a cyclic borane compound. Examples of such cyclic borane compounds include those having nitrogen or sulfur as a ringforming member, such as morpholine borane, piperidine borane, pyridine borane, piperazine borane, 2,6-lutidine borane, 4-methylmorpholine borane, and 1,4-oxathiane borane, and also N,N-diethylaniline borane.

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